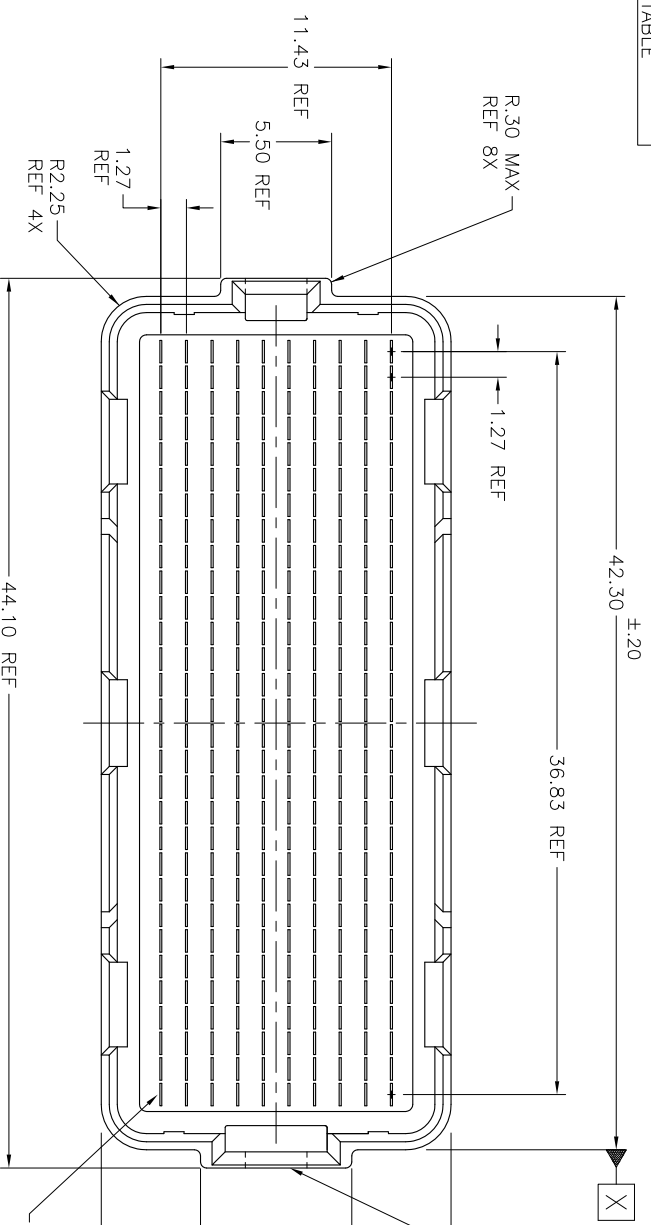


PRODUCT NUMBER
SEE TABLE

1 | 2

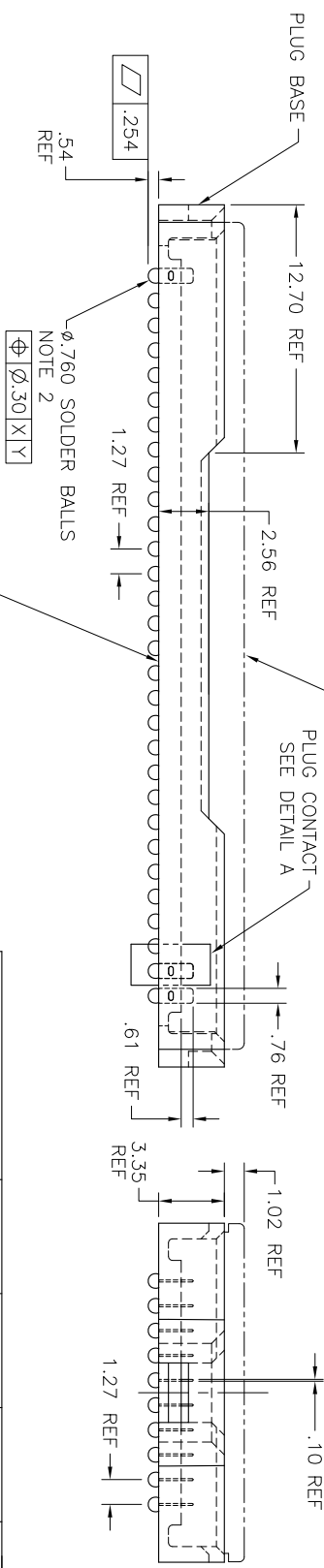
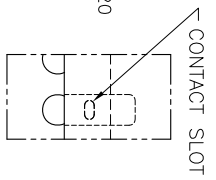
3

4



OPEN KNT LINES PERMISSIBLE IN PLASTIC BASE COMPONENT KEY SLOT AREAS (BOTH ENDS). SEE NOTE 8.

DETAIL A
SCALE 6:1



CONTINUOUS OPEN KNT LINE CRACKS (TRAVERSING THE ENTIRE BODY LENGTH OF THE CONNECTOR) WHICH CAUSE CRITICAL-TO-FUNCTION DIMENSIONAL CHANGES THAT AFFECT THE CONNECTORS MECHANICAL ALIGNMENT FEATURES ARE NOT PERMISSIBLE. SEE NOTE 6.

mat'l code	surface	tolerance	projection	product family
SEE NOTE 1.	ASME Y14.5	ASME Y14.5	MM	MEG-ARRAY
lfr	ecn no.	dr	date	title
A	V05-0324	DAI	2006/04/19	0mm PLUG ASSY
B	V06-0560	LP	2006/07/18	10 X 30 = 300 POS.
C	V08-0084	LP	2008/05/07	
D	V-13789	DCH	2012/1/21	
		engr	DINGRAM	7/21/04
		chn	D.HARPER	7/21/04
		appd	D.HARPER	7/21/04
sheet index	revision	1	2	3
Sheet	Sheet	1	2	3



10043343

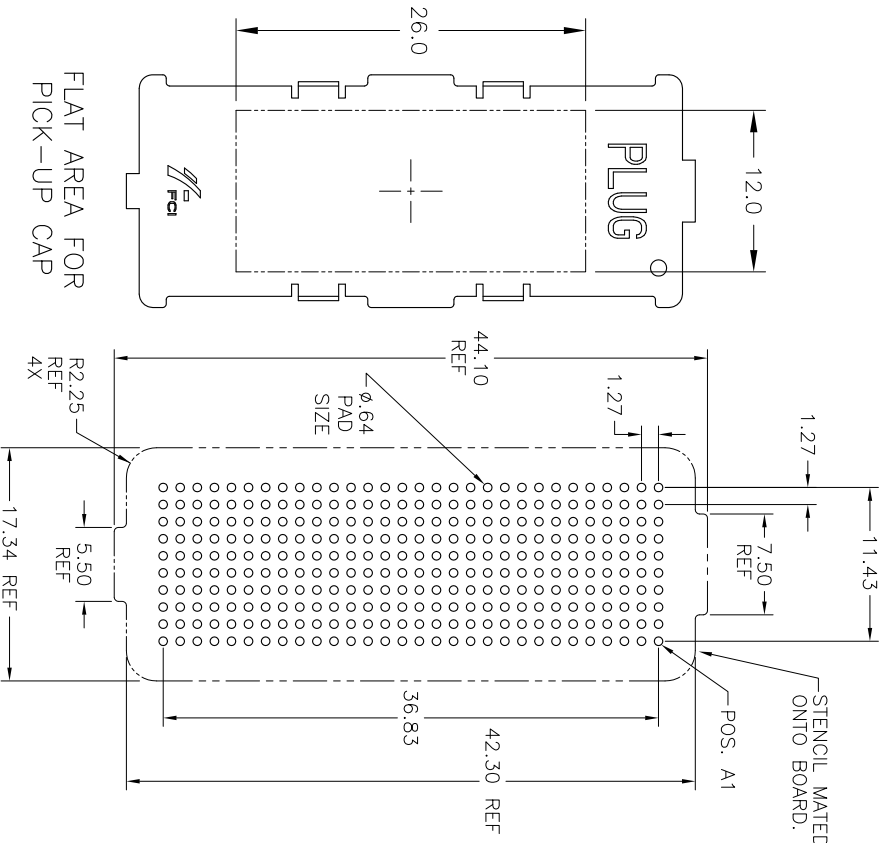
CUSTOMER Drawing

PRODUCT NUMBER
SEE TABLE

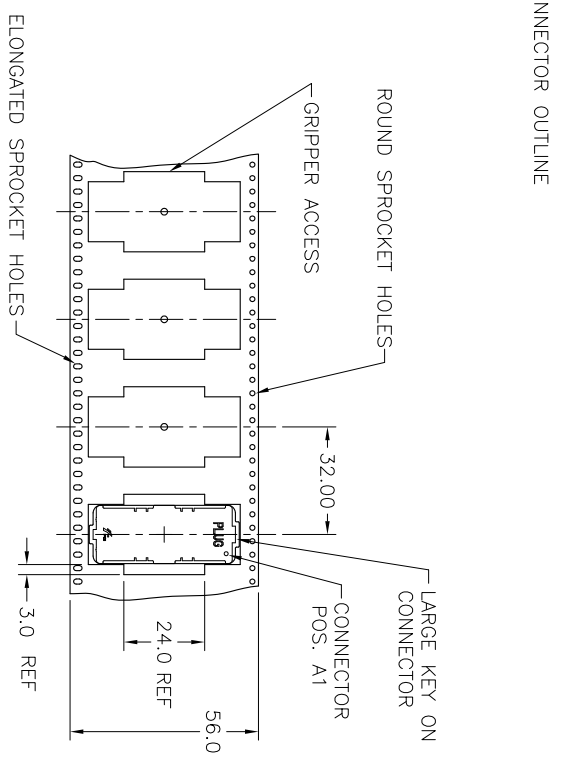
1 2

3

4



BOARD PATTERN



TAPE & REEL PACKAGING SCALE: NONE
PER EIA 481-3

CONFIDENTIAL

mat'l code		surface		tolerance		projection		product family	
SEE NOTE 1.		ASME Y14.5		ASME Y14.5		MM		MEG-ARRAY	
lfr	ecn no	dr	date	tolerances unless otherwise specified		title		sheet no	
D				X+3		10mm PLUG ASSY		sheet 2 of	
				XX+13		10 X 30 = 300 POS.		size	
				XXX+051		SCALE 2:1		A4	
		dr	D.INGRAM	7/21/04					
		enfr	D.HARPER	7/21/04					
		chr	D.HARPER	7/21/04					
		apprd	D.HARPER	7/21/04					
sheet index	revision								



FCIconnect.com

PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
10043343-102			SnPb
10043343-102LF	YES	30u" (0.76um) Au OVER Ni	SnAgCu LEAD FREE (6)(7)
10043343-192			SnPb
10043343-192LF	YES	30u" (0.76um) GXT OVER Ni	SnAgCu LEAD FREE (6)(7)
10043343-202			SnPb
10043343-202LF	YES	50u" (1.27um) Au SPECIAL	SnAgCu LEAD FREE (6)(7)
10043343-292			SnPb
10043343-292LF	YES	50u" (1.27um) GXT SPECIAL	SnAgCu LEAD FREE (6)(7)

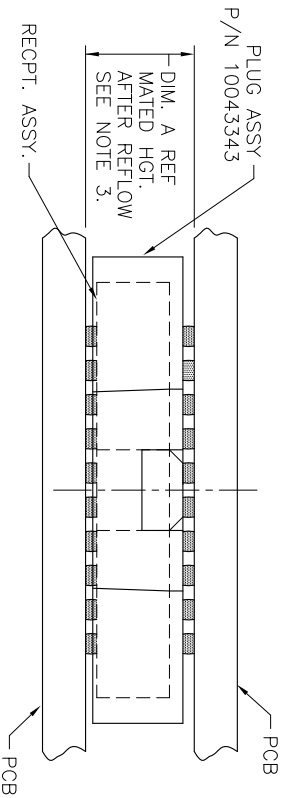
NOTES:

- ① MAT'L:
HOUSING: LCP
CONTACT: COPPER ALLOY

PLATING:

CONTACT: (SEE TABLE ON SHEETS)
SOLDER BALL: (SEE TABLE ON SHEETS)
EUTECTIC SnPb OR LEAD FREE
95.5Sn/4Ag/0.5Cu

- ② SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- ③ MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- ④ PLATING FOR INDICATED -2XX SERIES PART NOS. MEETS THE REQUIREMENTS OF CENTRAL OFFICE ENVIRONMENT (25 YEAR LIFE EXPECTANCY).
- ⑤ PLATING FOR INDICATED -2XX SERIES PART NOS. IS Au OR GXT OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.
- ⑥ FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- ⑦ THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION
- ⑧ KNOT LINE: SLIGHT VISIBLE MARKS (USUALLY A LINE) THE DIRECTION AND MEETING POINT OF THE PLASTIC RESIN FLOW FRONTS TRAVELING AROUND ANY OBSTRUCTIONS TO THE RESIN FLOW VIA THE REQUIRED MOLD TOOLING.



* 84502 NOT AVAILABLE IN TELCORDIA/NORTEL VERSION.

MATED HEIGHT AFTER REFLOW IS BASED ON Ø .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS SCALE: NONE

mat'l code	surface	tolerance	projection	product family
SEE NOTE 1.	ASME Y14.5	ASME Y14.5	MM	MEG-ARRAY
lit	ecp no	dr	date	tolerances unless otherwise specified
D				X-3
				XX-13
				XXX-051
				Scale 2:1
dr	D:INGRAM	7/21/04		
enrg	D:HARPER	7/21/04		
chr	D:HARPER	7/21/04		
apprd	D:HARPER	7/21/04		
sheet	revision			
index	sheet			



dwg no 10043343
sheet 3 of 4
CUSTOMER Drawing